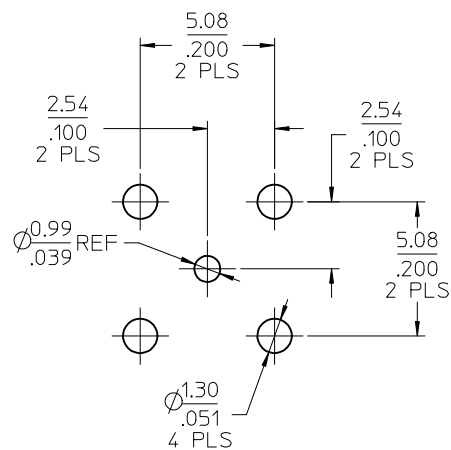
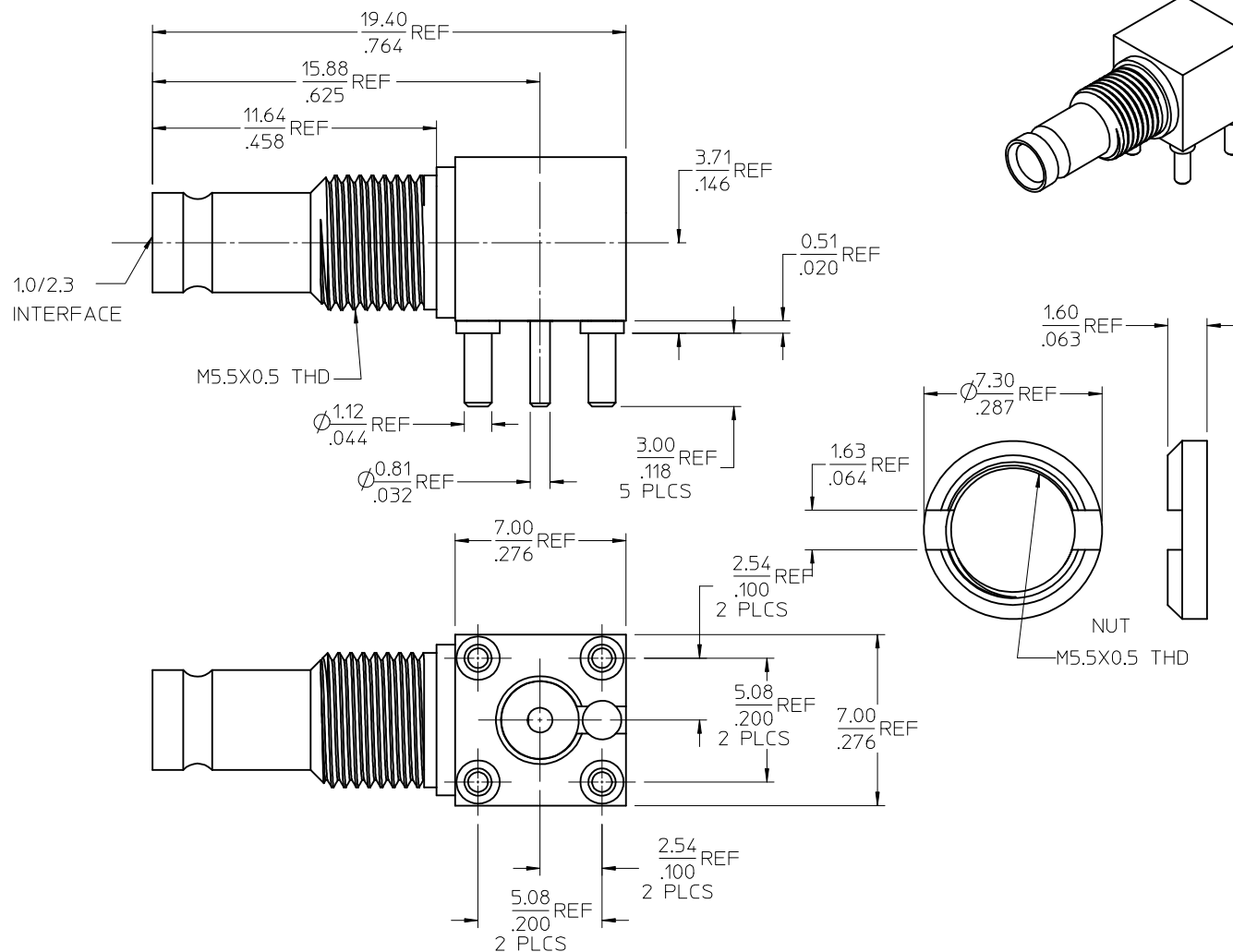


INSULATOR: TEFLON



RECOMMENDED HOLE LAYOUT



73174-0411	GOLD
73174-0410	NICKEL
PART NO.	PLATING

- $\frac{1}{64}$ ALL OVER.
- NO CHATTER OR NON-UNIFORM SURFACE FINISH ALLOWED.
- PARTS TO BE FREE OF BURRS & SHARP EDGES 0.13(0.005) MAX BREAK.
- EXTERNAL THREADS TO BE ROLLED OR SINGLE POINT.
- DIAMETERS TO BE CONCENTRIC WITHIN 0.08(0.003) TIR.

CHG: PCB CENTER
HOLE WAS $\varnothing.051$
REMOVED PLATING
THICKNESS

EC NO: URF2009-0277	2008/11/24
DRWN: JWIENER	2008/11/24
CH'KD: SHAH	2008/11/24
APPR: JWIENER	2008/11/24
REV	DESCRIPTION

QUALITY SYMBOLS	
	=0
	=0

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE	
MM/IN	
DRAWN BY	DATE
SSS	2004/03/02
CHECKED BY	DATE
TEF	2004/03/02
APPROVED BY	DATE
GMH	2004/03/02

SCALE	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
TITLE	1.0/2.3 JACK, R/A PCB 50 OHMS, EWR-2361 1.0/2.3-J/PCB	
	MOLEX INCORPORATED	

MATERIAL NO.	DOCUMENT NO.	SHEET NO.
SEE TABLE	SD-73174-041	1 OF 1
SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	